

ABSTRACT

A temporary protective film for semiconductor encapsulation molding, including a support film and an adhesive layer. The adhesive layer contains a thermoplastic resin and a low-molecular-weight additive having a molecular weight of less than 1000. The adhesive layer is configured so that X2 is smaller than X1 when a proportion of an oxygen atom in a surface of a copper plate after the temporary protective film for semiconductor encapsulation molding is bonded to the surface of the copper plate in a direction in which the adhesive layer comes into contact with the copper plate to form a bonded body having the copper plate and the temporary protective film for semiconductor encapsulation molding, and then the bonded body is heated at 180°C for 1 hour is designated as X1, and a proportion of the oxygen atom in the surface of the copper plate after the bonded body is subjected to a thermal treatment of further heating at 400°C for 2 minutes is designated as X2.

Fig. 1